

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source voltage			V_{DSS}	60	V
Gate-Source voltage (Note 5)		(Note 5)	V_{GS}	±20	V
Single Pulsed Avalanche Energy (Note 11)		(Note 11)	E _{AS}	37.5	mJ
Single Pulsed Avalanche Current (Note 11)		(Note 11)	IAS	5.0	А
		(Note 7)		8.5	
Continuous Drain current	$V_{GS} = 10V$	$T_A = 70^{\circ}C \text{ (Note 7)}$	I_{D}	6.8	Α
		(Note 6)		6.0	
Pulsed Drain current	V _{GS} = 10V	(Note 8)	I _{DM}	22.2	Α
Continuous Source current (Body diode) (Note 7)		(Note 7)	I _S	10.2	Α
Pulsed Source current (Body diode) (Note 8)		(Note 8)	I _{SM}	22.2	А

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

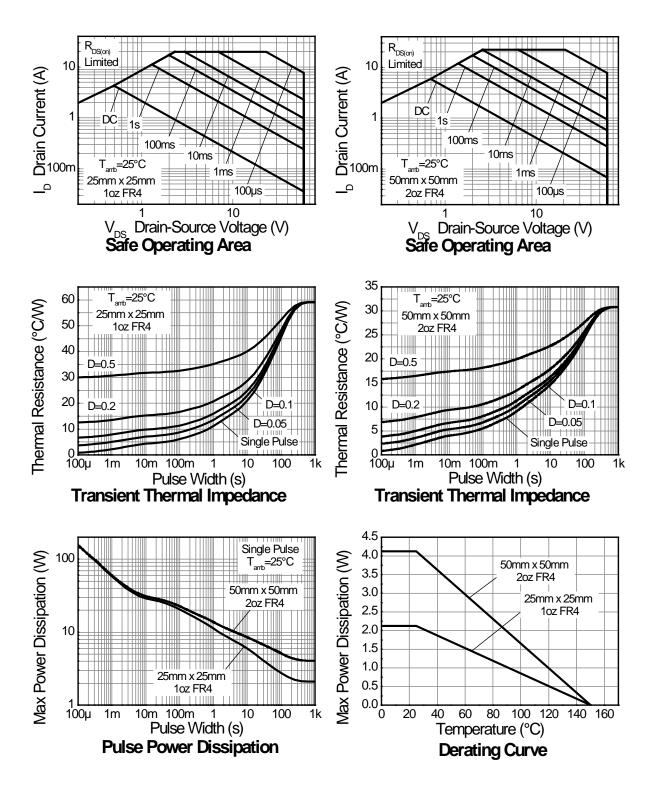
Characteristic	Symbol	Value	Unit		
	(Note 6)	4.12 33			
Power dissipation	(Note 7)	PD	8.49	W mW/°C	
Linear derating factor			67.9		
	(Note 9)		2.12		
			16.9		
	(Note 6)		30.3		
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{ heta JA}$	14.7	°C/W	
	(Note 9)		59.0		
Thermal Resistance, Junction to Lead (Note 10)		$R_{ heta JL}$	3.09		
Operating and storage temperature range	T _J , T _{STG}	-55 to +150	°C		

Notes:

- 5. AEC-Q101 V_{GS} maximum is ±16V.
- 6. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 7. Same as note 2, except the device is measured at $t \le 10$ sec.
- 8. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature. 9. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is
- For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 10. Thermal resistance from junction to solder-point (at the end of the drain lead).
- 11. UIS in production with L = 3.0mH, I_{AS} = 5.0Å, R_{G} = 25 $^{\bullet}$, V_{DD} = 50V, starting T_{J} = 25 $^{\circ}$ C



Thermal Characteristics



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Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

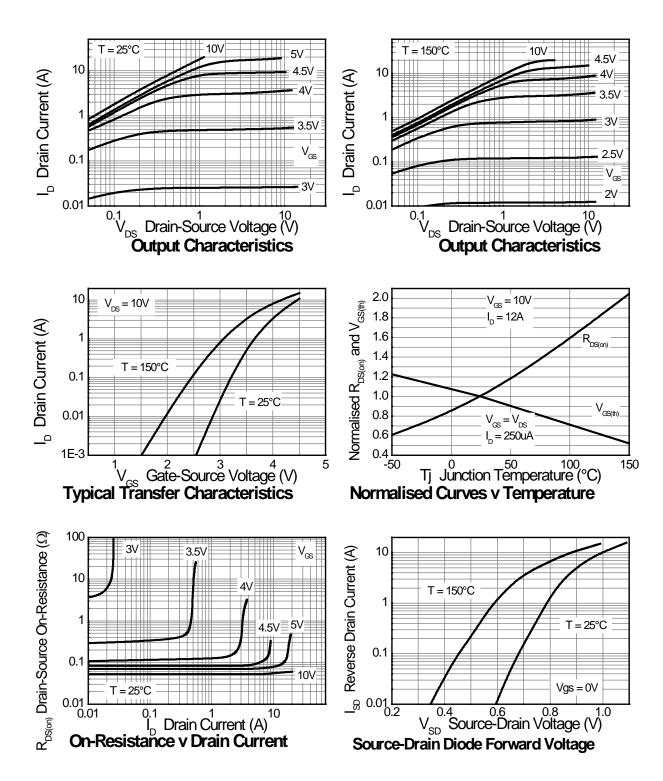
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$I_D = 250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I _{DSS}		_	0.5	μΑ	V _{DS} = 60V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V _{GS} = ±20V, V _{DS} = 0V	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	1.0		3.0	٧	$I_D=250\mu A,\ V_{DS}=V_{GS}$	
Static Drain-Source On-Resistance (Note 12)	D		_	0.068	0	V _{GS} = 10V, I _D = 12A	
Static Dialii-Source Off-Resistance (Note 12)	R _{DS (ON)}	_		0.100	Ω	V _{GS} = 4.5V, I _D = 6A	
Forward Transconductance (Notes 12 & 13)	g fs	_	19.7	_	S	V _{DS} = 15V, I _D = 12A	
Diode Forward Voltage (Note 12)	V _{SD}	_	0.98	1.15	V	I _S = 12A, V _{GS} = 0V	
Reverse recovery time (Note 13)	t _{rr}		145	_	ns	-I _S = 12A, di/dt= 100A/μs	
Reverse recovery charge (Note 13)	Q _{rr}	_	929	_	nC		
DYNAMIC CHARACTERISTICS (Note 13)	DYNAMIC CHARACTERISTICS (Note 13)						
Input Capacitance	C _{iss}		502	_	pF		
Output Capacitance	Coss	_	45.7	_	pF	V _{DS} = 30V, V _{GS} = 0V -f= 1MHz	
Reverse Transfer Capacitance	C _{rss}		27.1	_	pF		
Total Gate Charge	Q_g		5.55	_	nC	V _{GS} = 4.5V	
Total Gate Charge	Q_g		10.3	_	nC	V _{DS} = 30V I _D = 12A	
Gate-Source Charge	Q_{gs}	_	1.6	_	nC		
Gate-Drain Charge	Q_{gd}	_	3.5	_	nC		
Turn-On Delay Time (Note 14)	t _{D(on)}	_	3.6	_	ns		
Turn-On Rise Time (Note 14)	tr	_	10.8		ns	V_{DD} = 30V, V_{GS} = 10V I_{D} = 12A, $R_{G} \cong 6.0\Omega$	
Turn-Off Delay Time (Note 14)	t _{D(off)}	_	11.9		ns		
Turn-Off Fall Time (Note 14)	t _f	_	8.7	_	ns		

Notes:

^{12.} Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
13. For design aid only, not subject to production testing.
14. Switching characteristics are independent of operating junction temperatures.

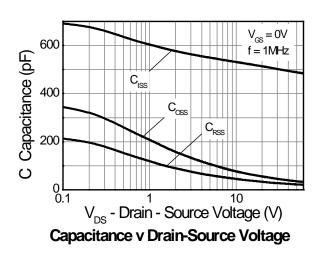


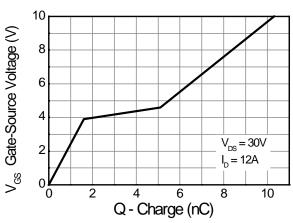
Typical Characteristics



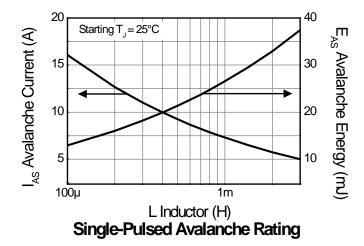


Typical Characteristics - continued



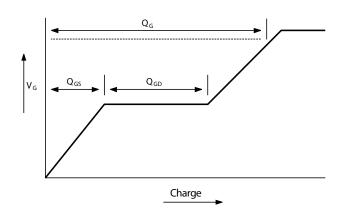


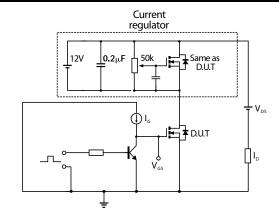
Gate-Source Voltage v Gate Charge





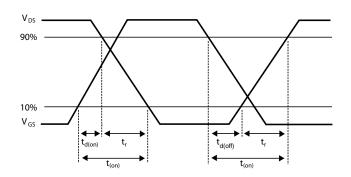
Test Circuits

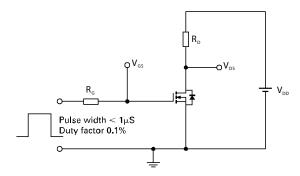




Basic gate charge waveform

Gate charge test circuit



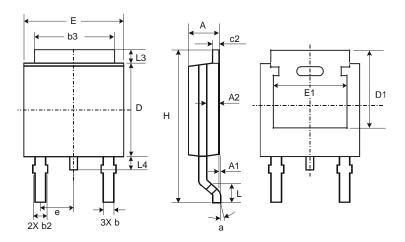


Switching time waveforms

Switching time test circuit

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

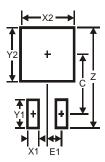


TO252				
Dim	Min	Max	Тур	
Α	2.19	2.39	2.29	
A1	0.00	0.13	0.08	
A2	0.97	1.17	1.07	
b	0.64	0.88	0.783	
b2	0.76	1.14	0.95	
b3	5.21	5.46	5.33	
c2	0.45	0.58	0.531	
D	6.00	6.20	6.10	
D1	5.21	_	-	
е	_	_	2.286	
Е	6.45	6.70	6.58	
E1	4.32	_	1	
Н	9.40	10.41	9.91	
٦	1.40	1.78	1.59	
L3	0.88	1.27	1.08	
L4	0.64	1.02	0.83	
а	0°	10°	_	
All Dimensions in mm				



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
Z	11.6		
X1	1.5		
X2	7.0		
Y1	2.5		
Y2	7.0		
С	6.9		
E1	2.3		

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